

Electronic Patent Application Fee Transmittal

Application Number:	10055568			
Filing Date:	22-Jan-2002			
Title of Invention:	Chip package with die and substrate			
First Named Inventor/Applicant Name:	Mou-Shiung Lin			
Filer:	Winston Hsu			
Attorney Docket Number:	MEGP0004USA			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180